Data Sheet: Technical Data

MMA2301KEG Rev 1, 11/2012

VRoHS

Surface Mount Micromachined Accelerometer

The MMA series of silicon capacitive, micromachined accelerometers feature signal conditioning, a 4-pole low pass filter and temperature compensation. Zero-g offset full scale span and filter cut-off are factory set and require no external devices. A full system self-test capability verifies system functionality.

Features

- · Integral Signal Conditioning
- Linear Output
- · Ratiometric Performance
- 4th Order Bessel Filter Preserves Pulse Shape Integrity
- · Calibrated Self-test
- Low Voltage Detect, Clock Monitor, and EPROM Parity Check Status
- · Transducer Hermetically Sealed at Wafer Level for Superior Reliability
- Robust Design, High Shocks Survivability
- · Robust Design, High Shock Survivability
- Qualified AEC-Q100, Rev. F Grade 2 (-40°C/+105°C)

Typical Applications

- Vibration Monitoring and Recording
- Impact Monitoring

ORDERING INFORMATION					
Device Name	Temperature Range	Case No.	Package		
MMA2301EG	−40° to 125°C	475-01	SOIC-16		
MMA2301EGR2	–40° to 125°C	475-01	SOIC-16, Tape & Reel		
MMA2301KEG*	–40° to 125°C	475-01	SOIC-16		
MMA2301KEGR2*	–40° to 125°C	475-01	SOIC-16, Tape & Reel		

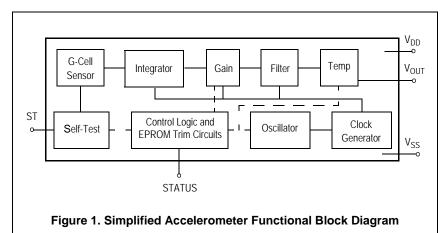
^{*}Part number sourced from a different facility.

MMA2301KEG

MMA2301KEG: X-AXIS SENSITIVITY
MICROMACHINED
ACCELEROMETER
±200g



KEG SUFFIX (Pb-FREE) 16-LEAD SOIC CASE 475-01



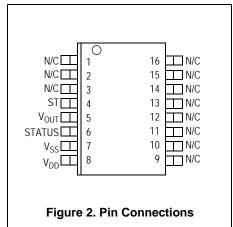






Table 1. Maximum Ratings

(Maximum ratings are the limits to which the device can be exposed without causing permanent damage.)

Rating	Symbol	Value	Unit
Powered Acceleration (all axes)	G _{pd}	1500	g
Unpowered Acceleration (all axes)	G _{upd}	2000	g
Supply Voltage	V_{DD}	-0.3 to +7.0	V
Drop Test ⁽¹⁾	D _{drop}	1.2	m
Storage Temperature Range	T _{stg}	-40 to +125	°C

^{1.} Dropped onto concrete surface from any axis.

ELECTRO STATIC DISCHARGE (ESD)

WARNING: This device is sensitive to electrostatic discharge.

Although the accelerometers contain internal 2 kV ESD protection circuitry, extra precaution must be taken by the user to protect the chip from ESD. A charge of over 2000 volts can accumulate on the human body or associated test equipment. A charge of this magnitude can alter the

performance or cause failure of the chip. When handling the accelerometer, proper ESD precautions should be followed to avoid exposing the device to discharges which may be detrimental to its performance.



Table 2. Operating Characteristics

(Unless otherwise noted: $-40^{\circ}C \le T_A \le +105^{\circ}C$, $4.75 \le VDD \le 5.25$, Acceleration = 0g, Loaded output)⁽¹⁾

Characteristic	Symbol	Min	Тур	Max	Unit
Operating Range ⁽²⁾ Supply Voltage ⁽³⁾ Supply Current Operating Temperature Range Acceleration Range	V _{DD} I _{DD} T _A 9FS	4.75 3.0 -40 —	5.0 — — 225	5.25 6.0 +125 —	V mA °C g
Output Signal Zero g ($T_A = 25^{\circ}C$, $V_{DD} = 5.0 \text{ V}$) ⁽⁴⁾ Zero g Sensitivity ($T_A = 25^{\circ}C$, $V_{DD} = 5.0 \text{ V}$) ⁽⁵⁾ Sensitivity Bandwidth Response Nonlinearity	VOFF VOFF,V S S _V f _{-3dB} NL _{OUT}	2.4 0.46 V _{DD} 9.5 1.86 360 -1.0	2.5 0.50 V _{DD} 10.0 2.0 400	2.6 0.54 V _{DD} 10.5 2.14 440 1.0	V V mV/g mV/g/V Hz % FSO
Noise RMS (.01-1 kHz) Power Spectral Density Clock Noise (without RC load on output) ⁽⁶⁾	n _{RMS} n _{PSD} n _{CLK}	_ _ _	 110 2.0	2.8 — —	mVrms μV/(Hz ^{1/2}) mVpk
Self-Test Output Response ⁽⁷⁾ Input Low Input High Input Loading ⁽⁸⁾ Response Time ⁽⁹⁾	9st V _{IL} V _{IH} I _{IN} t _{ST}	24 V _{SS} 0.7 x V _{DD} -30	30 — — -100 2.0	36 0.3 x V _{DD} V _{DD} -260 10	g V V μA ms
Status ⁽¹⁰⁾ (11) Output Low (I_{load} = 100 μ A) Output High (I_{load} = 100 μ A)	V _{OL} V _{OH}	— V _{DD} -0.8	_ _	0.4	V V
Minimum Supply Voltage (LVD Trip)	V_{LVD}	2.7	3.25	4.0	V
Clock Monitor Fail Detection Frequency	f _{min}	50	_	260	kHz
Output Stage Performance Electrical Saturation Recovery Time ⁽¹²⁾ Full Scale Output Range (I _{OUT} = 200 μA) Capacitive Load Drive ⁽¹³⁾ Output Impedance	t _{DELAY} V _{FSO} C _L Z _O	 0.25 	0.2 — — 300	— V _{DD} -0.25 100 —	ms V pF Ω
Mechanical Characteristics Transverse Sensitivity ⁽¹⁴⁾ Package Resonance	V _{XZ,YZ}	_ _	_ 10	5.0 —	% FSO kHz

- 1. For a loaded output the measurements are observed after an RC filter consisting of a 1 kΩ resistor and a 0.01 μF capacitor to ground.
- 2. These limits define the range of operation for which the part will meet specification.
- 3. Within the supply range of 4.75 and 5.25 volts, the device operates as a fully calibrated linear accelerometer. Beyond these supply limits the device may operate as a linear device but is not guaranteed to be in calibration.
- The device can measure both + and acceleration. With no input acceleration the output is at midsupply. For positive acceleration the output will increase above V_{DD}/2 and for negative acceleration the output will decrease below V_{DD}/2.
- 5. The device is calibrated at 35g.
- 6. At clock frequency ≈ 70 kHz.
- 7. ΔV_{OFF} calculated with typical sensitivity.
- 8. The digital input pin has an internal pull-down current source to prevent inadvertent self test initiation due to external board level leakages.
- 9. Time for the output to reach 90% of its final value after a self-test is initiated.
- 10. The Status pin output is not valid following power-up until at least one rising edge has been applied to the self-test pin. The Status pin is high whenever the self-test input is high, as a means to check the connectivity of the self-test and Status pins in the application.
- 11. The Status pin output latches high if a Low Voltage Detection or Clock Frequency failure occurs, or the EPROM parity changes to odd. The Status pin can be reset low if the self-test pin is pulsed with a high input for at least 100 us, unless a fault condition continues to exist.
- 12. Time for amplifiers to recover after an acceleration signal causing them to saturate.
- 13. Preserves phase margin (60°) to guarantee output amplifier stability.
- 14. A measure of the device's ability to reject an acceleration applied 90° from the true axis of sensitivity.



PRINCIPLE OF OPERATION

The Freescale accelerometer is a surface-micromachined integrated-circuit accelerometer.

The device consists of a surface micromachined capacitive sensing cell (g-cell) and a CMOS signal conditioning ASIC contained in a single integrated circuit package. The sensing element is sealed hermetically at the wafer level using a bulk micromachined "cap" wafer.

The g-cell is a mechanical structure formed from semiconductor materials (polysilicon) using semiconductor processes (masking and etching). It can be modeled as two stationary plates with a moveable plate in-between. The center plate can be deflected from its rest position by subjecting the system to an acceleration (Figure 3).

When the center plate deflects, the distance from it to one fixed plate will increase by the same amount that the distance to the other plate decreases. The change in distance is a measure of acceleration.

The g-cell plates form two back-to-back capacitors (Figure 4). As the center plate moves with acceleration, the distance between the plates changes and each capacitor's value will change, ($C = A\epsilon/D$). Where A is the area of the

plate, ϵ is the dielectric constant, and D is the distance between the plates.

The CMOS ASIC uses switched capacitor techniques to measure the g-cell capacitors and extract the acceleration data from the difference between the two capacitors. The ASIC also signal conditions and filters (switched capacitor) the signal, providing a high level output voltage that is ratiometric and proportional to acceleration.

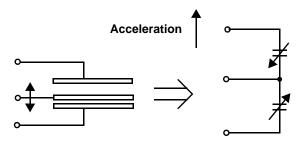


Figure 3. Transducer Physical Model and Equivalent Circuit Model

SPECIAL FEATURES

Filtering

The Freescale accelerometers contain an onboard 2-pole switched capacitor filter. A Bessel implementation is used because it provides a maximally flat delay response (linear phase) thus preserving pulse shape integrity. Because the filter is realized using switched capacitor techniques, there is no requirement for external passive components (resistors and capacitors) to set the cut-off frequency.

Self-Test

The sensor provides a self-test feature that allows the verification of the mechanical and electrical integrity of the accelerometer at any time before or after installation. This feature is critical in applications such as automotive airbag systems where system integrity must be ensured over the life of the vehicle. A fourth "plate" is used in the g-cell as a self-test plate. When the user applies a logic high input to the self-test pin, a calibrated potential is applied across the self-test plate and the moveable plate. The resulting electrostatic

force
$$\left(F_{e} = \frac{1}{2} \varepsilon A \frac{V^{2}}{\sigma^{2}}\right)$$
 causes the center plate to deflect.

The resultant deflection is measured by the accelerometer's control ASIC and a proportional output voltage results. This procedure assures that both the mechanical (g-cell) and electronic sections of the accelerometer are functioning.

Status

Freescale accelerometers include fault detection circuitry and a fault latch. The Status pin is an output from the fault latch, OR'd with self-test, and is set high whenever the following event occurs:

Parity of the EPROM bits becomes odd in number.

The fault latch can be reset by a rising edge on the self-test input pin, unless one (or more) of the fault conditions continues to exist.



BASIC CONNECTIONS

PINOUT DESCRIPTION

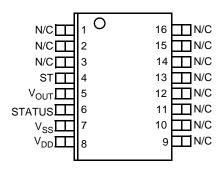


Table 3. Pin Descriptions

Pin No.	Pin Name	Description
1 thru 3	N/C	Leave unconnected.
4	ST	Logic input pin used to initiate self-test.
5	V _{OUT}	Output voltage of the accelerometer.
6	STATUS	Logic output pin to indicate fault.
7	V _{SS}	The power supply ground.
8	V_{DD}	The power supply input.
9 thru 13	Trim pins	Used for factory trim. Leave unconnected.
14 thru 16	_	No internal connection. Leave unconnected.

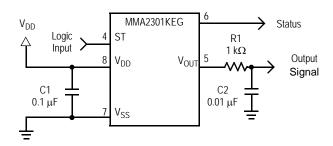


Figure 4. SOIC Accelerometer with Recommended Connection Diagram

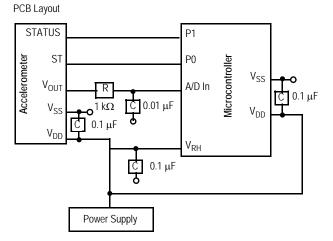


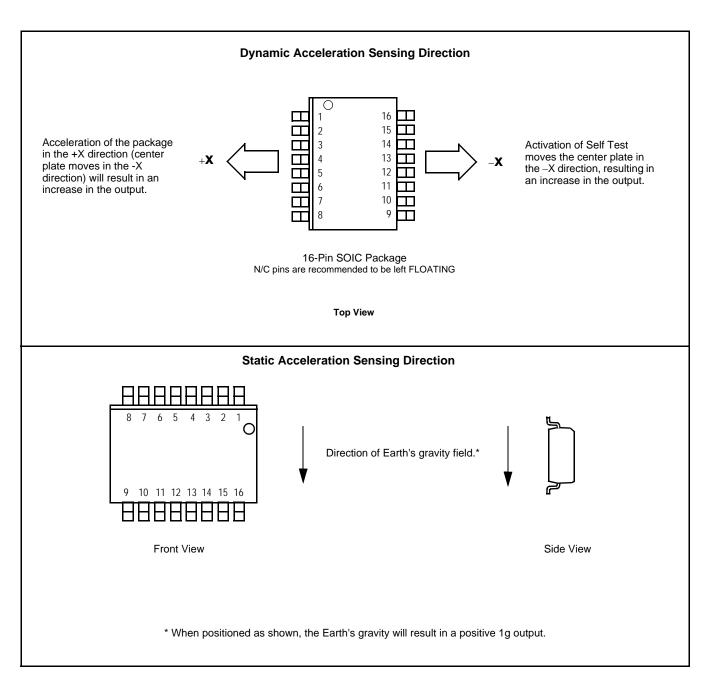
Figure 5. Recommend PCB Layout for Interfacing Accelerometer to Microcontroller

NOTES:

- Use a 0.1 μF capacitor on V_{DD} to decouple the power source.
- Physical coupling distance of the accelerometer to the microcontroller should be minimal.
- Place a ground plane beneath the accelerometer to reduce noise, the ground plane should be attached to all of the open ended terminals shown in Figure 5
- Use an RC filter of 1 kΩ and 0.01 μF on the output of the accelerometer to minimize clock noise (from the switched capacitor filter circuit).
- PCB layout of power and ground should not couple power supply noise.
- Accelerometer and microcontroller should not be a high current path.

A/D sampling rate and any external power supply switching frequency should be selected such that they do not interfere with the internal accelerometer sampling frequency. This will prevent aliasing errors.







MINIMUM RECOMMENDED FOOTPRINT FOR SURFACE MOUNTED APPLICATIONS

Surface mount board layout is a critical portion of the total design. The footprint for the surface mount packages must be the correct size to ensure proper solder connection interface between the board and the package. With the correct

footprint, the packages will self-align when subjected to a solder reflow process. It is always recommended to design boards with a solder mask layer to avoid bridging and shorting between solder pads.

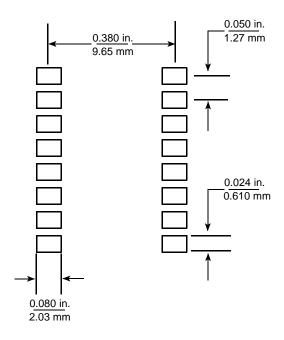
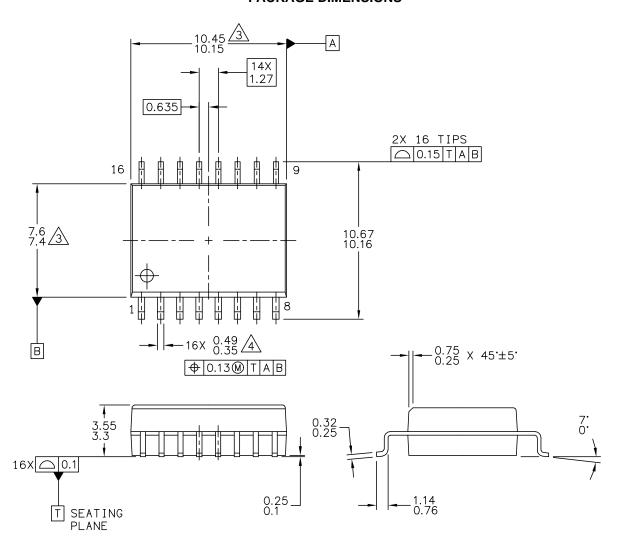


Figure 6. Footprint SOIC-16 (Case 475-01)

7



PACKAGE DIMENSIONS



© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	MECHANICA	L OUTLINE	PRINT VERSION NO	OT TO SCALE
TITLE:		DOCUMENT NO): 98ASB16926C	REV: C
16 LEAD SOIC ACCELEROMETER	ı	CASE NUMBER	R: 475–01	17 MAR 2005
, , o o e e e e e e e e e e e e e e e e		STANDARD: NO	N-JEDEC	

PAGE 1 OF 2

CASE 475-01 ISSUE C 16-LEAD SOIC



PACKAGE DIMENSIONS

NOTES:

- 1. ALL DIMENSONS ARE IN MILLIMETERS.
- 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.



THESE DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.

MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 PER SIDE.



THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION.
PROTRUSIONS SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.75

© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	MECHANICA	L OUTLINE	PRINT VERSION NO	OT TO SCALE
TITLE:		DOCUMENT NO): 98ASB16926C	REV: C
16 LEAD SOIC ACCELEROMETER		CASE NUMBER	R: 475–01	17 MAR 2005
//OOLLENOMETEN		STANDARD: NO	N-JEDEC	

PAGE 2 OF 2

CASE 475-01 ISSUE C 16-LEAD SOIC

MMA2301KEG



Table 4. Revision History

Revision number	Revision date	Description of changes
1	11/2012	Table 2. Operating Characteristics, added footnote for Self-Test Output Response, updated page 4: Principle of Operation



How to Reach Us:

Home Page: freescale.com

Web Support: freescale.com/support

Information in this document is provided solely to enable system and software implementers to use Freescale products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits based on the information in this document.

Freescale reserves the right to make changes without further notice to any products herein. Freescale makes no warranty, representation, or guarantee regarding the suitability of its products for any particular purpose, nor does Freescale assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters that may be provided in Freescale data sheets and/or specifications can and do vary in different applications, and actual performance may vary over time. All operating parameters, including "typicals," must be validated for each customer application by customer's technical experts. Freescale does not convey any license under its patent rights nor the rights of others. Freescale sells products pursuant to standard terms and conditions of sale, which can be found at the following address: freescale.com/salestermsandconditions.

Freescale, the Freescale logo, Energy Efficient Solutions logo, are trademarks of Freescale Semiconductor, Inc., Reg. U.S. Pat. & Tm. Off. Xtrinsic is a trademark of Freescale Semiconductor, Inc. All other product or service names are the property of their respective owners.

© 2012 Freescale Semiconductor, Inc.





Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов:
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001:
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: <u>org@eplast1.ru</u>

Адрес: 198099, г. Санкт-Петербург, ул. Калинина,

дом 2, корпус 4, литера А.